

AH9247

General Description

The AH9247 is an ultra-sensitive Hall-effect switch with digital latched output, mainly designed for battery-operation, handheld equipments.

Special CMOS process is used for low-voltage and low-power requirement. A chopper stabilized amplifier improves stability of magnetic switch points. A sleep-awake logic controls the IC in sleep time or awake time. This function will reduce the average operating current of the IC. During the awake time, the output is changed with the magnetic flux density. During the sleep time, the output is latched in its previous state and the current consumption will reduce to some $\mu A. \ \ \,$

The IC switching behaviour is omnipolar, either north or south pole sufficient strength will turn the output on. If the magnetic flux density is larger than operating point (B_{OP}) , the output will be turned on; if it is less than releasing point (B_{RP}) , the output will be turned off.

The AH9247 is available in TO-92S-3, SOT-23-3 and DFN-2×2-3 packages which are optimized for most applications.

Features

- Micropower Operation
- 2.5 to 5.5V Power Supply
- Switching for Both Poles of a Magnet (Omnipolar)
- Stabilized Chopper
- Superior Temperature Stability
- Digital Output Signal
- Built-in Pull-up Resistor
- ESD (HBM) 6000V

Applications

- Cover Switch in Notebook PC/PDA
- Handheld Wireless Application Awake Switch
- Magnet Switch in Low Duty Cycle Applications

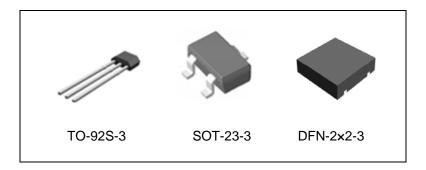
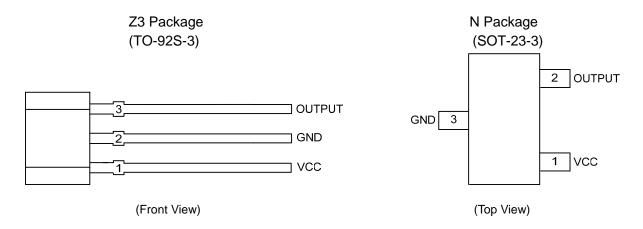


Figure 1. Package Types of AH9247



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Pin Configuration



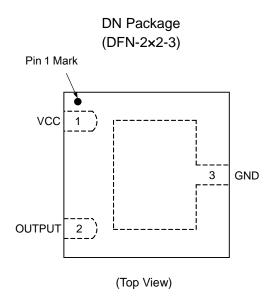


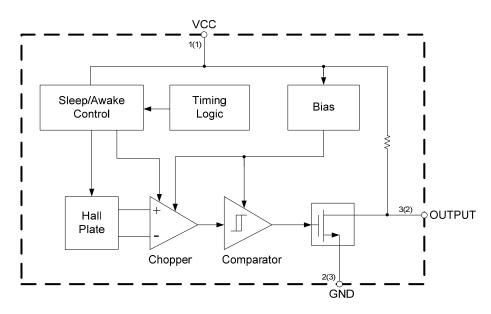
Figure 2. Pin Configuration of AH9247

Pin Description

	Pin Number		Pin Name	Function	
TO-92S-3	SOT-23-3	DFN-2×2-3	riii Name	runction	
1	1	1	VCC	Power supply pin	
2	3	3	GND	Ground pin	
3	2	2	OUTPUT	Output pin	

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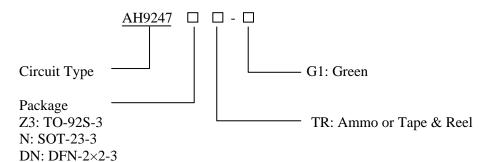
Functional Block Diagram



A (B) A for TO-92S-3 B for SOT-23-3 and DFN-2×2-3

Figure 3. Functional Block Diagram of AH9247

Ordering Information



Package	Temperature Range	Part Number	Marking ID	Packing Type
TO-92S-3		AH9247Z3TR-G1	9247	Ammo
SOT-23-3	-40 to 85°C	AH9247NTR-G1	GX8	Tape & Reel
DFN-2×2-3		AH9247DNTR-G1	JF	Tape & Reel

BCD Semiconductor's Pb-free products, as designated with "G1" suffix in the part number, are RoHS compliant and green.



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Absolute Maximum Ratings (T_A=25°C, Note 1)

Parameter	Symbol	Value		Unit
Supply Voltage	V_{CC}	7		V
Supply Current (Fault)	I_{CC}	6	6	
Output Voltage	V_{OUT}	7		V
Output Current	I _{OUT}	2	2	
Magnetic Flux Density	В	Unlimited		Gauss
		TO-92S-3	400	
Power Dissipation	P_D	SOT-23-3	230	mW
		DFN-2×2-3	230	
Storage Temperature	T_{STG}	-55 to	-55 to 150	
Junction Temperature	T_{J}	150		°C
ESD (Human Body Model) (Note 2)		6000		V
ESD (Machine Model) (Note 2)		400		V

Note 1: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

Note 2: Electronic semiconductor products are sensitive to Electro Static Discharge (ESD). Always observe Electro Static Discharge control procedures whenever handling semiconductor products.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
Supply Voltage	V_{CC}	2.5	5.5	V
Operating Temperature	T _{OP}	-40	85	°C



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Electrical Characteristics

 $V_{CC}=3V$, $T_A=25$ °C, unless otherwise specified.

Parameter	Symbol	Conditions	Min	Тур	Max	Units
Supply Voltage	V_{CC}	Operating	2.5	3	5.5	V
	I_{AW}	Awake		1.8	3	mA
Supply Current	I_{SL}	Sleep		4	10	μΑ
	I_{AVG}	Average		8	15	μΑ
Output Current	I_{OUT}				1.0	mA
Saturation Voltage	V_{SAT}	I _{OUT} =1.0mA			0.4	V
Awake Mode Time	t_{AW}	Operating		120		μs
Sleep Mode Time	$t_{ m SL}$	Operating		80	120	ms
Duty Cycle	D			0.15		%
Chopper Frequency	f_{C}			15		kHz

Magnetic Characteristics (Note 3)

 V_{CC} =3V, T_A =25°C, unless otherwise specified.

For TO-92S-3 Package

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
	B _{OPS}	South pole to branded side B>B _{OPS} , V _{OUT} =low(output on)	15	30	55	Gauss
Operating Point	B _{OPN}	North pole to branded side B>B _{OPN} , V _{OUT} =low(output on)	-55	-30	-15	Gauss
Releasing Point	B_{RPS}	South pole to branded side B <b<sub>RPS,V_{OUT}=high(output off)</b<sub>	5	20	45	Gauss
	B_{RPN}	North pole to branded side B <b<sub>RPN, V_{OUT}=high(output off)</b<sub>	-45	-20	-5	Gauss
Hysteresis	B_{HYS}	B _{OPX} - B _{RPX} (Note4)		10		Gauss



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Magnetic Characteristics (Note 3) (Continued)

 V_{CC} =3V, T_A =25°C, unless otherwise specified.

For SOT-23-3 and DFN-2×2-3 Packages

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
	B _{OPS}	South pole to branded side B>B _{OPS} , V _{OUT} =low(output on)	20	30	40	Gauss
Operating Point	B _{OPN}	North pole to branded side B>B _{OPN} , V _{OUT} =low(output on)	-40	-30	-20 32	Gauss
D.L D.L.	B_{RPS}	South pole to branded side B <b<sub>RPS, V_{OUT}=high(output off)</b<sub>	5	20	32	Gauss
Releasing Point	B_{RPN}	North pole to branded side B <b<sub>RPN, V_{OUT}=high(output off)</b<sub>	-32	-20	-5	Gauss
Hysteresis	B_{HYS}	B _{OPX} - B _{RPX} (Note4)		10		Gauss

Note 3: The specifications stated here are guaranteed by design. 1 Gauss=0.1mT

Note 4: B_{OPX}=operating point (output turns on); B_{RPX}=releasing point (output turns off)

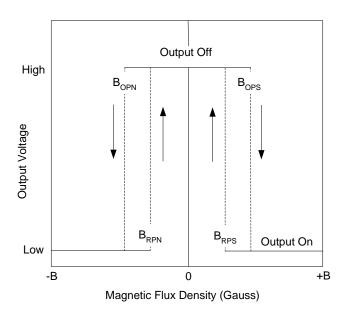


Figure 4. Output Voltage vs. Magnetic Flux Density



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Test Conditions

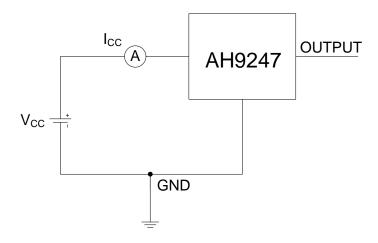


Figure 5. Average Supply Current (Note 5, Note 6)

Note 5: I_{CC} represents the average supply current. OUTPUT is open during measurement.

Note 6: The device is put under magnetic field with B<B_{RP}.

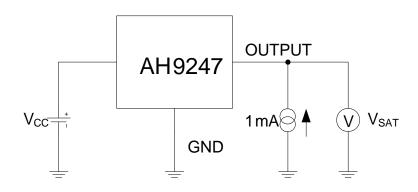


Figure 6. Output Saturation Voltage (Note 7, Note 8)

Note 7: The output saturation voltage V_{SAT} is measured at V_{CC} =2.5V and V_{CC} =5.5V

Note 8: The device is put under magnetic field with B>B_{OP}



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Test Conditions (Continued)

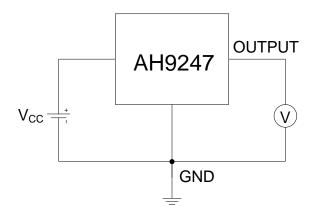


Figure 7. Magnetic Thresholds (Note 9, Note10)

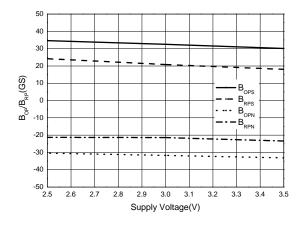
Note 9: B_{OP} is determined by putting the device under magnetic field swept from $B_{RP(min)}$ to $B_{OP(max)}$ until the output is switched on.

Note 10: B_{RP} is determined by putting the device under magnetic field swept from $B_{OP(max)}$ to $B_{RP(min)}$ until the output is switched off.



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Typical Performance Characteristics



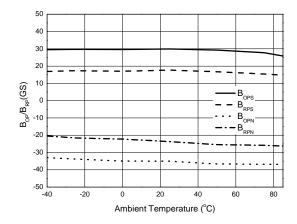
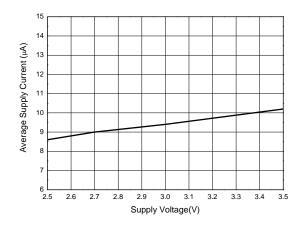


Figure 8. B_{OP}/B_{RP} vs. Supply Voltage

Figure 9. B_{OP}/B_{RP} vs. Ambient Temperature



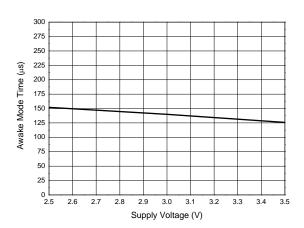


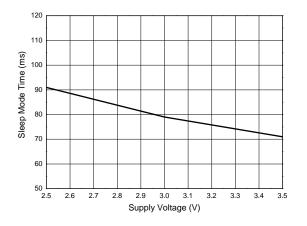
Figure 10. Average Supply Current vs. Supply Voltage

Figure 11. Awake Mode Time vs. Supply Voltage



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Typical Performance Characteristics (Characteristic)



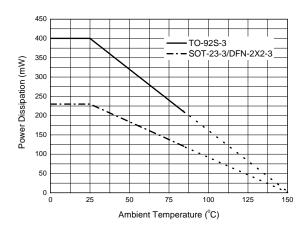


Figure 12. Sleep Mode Time vs. Supply Voltage

Figure 13. Power Dissipation vs. Ambient Temperature



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Typical Application

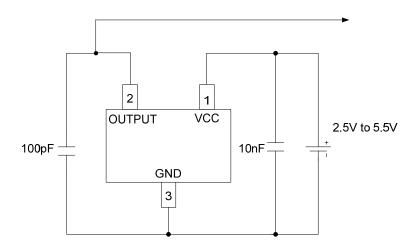


Figure 14. Typical Application Circuit of AH9247

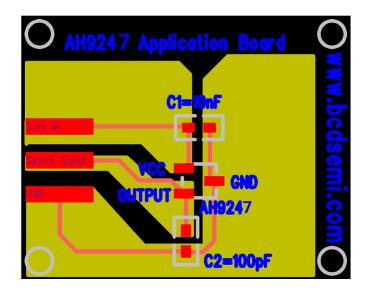


Figure 15. Typical Layout Pattern of AH9247 (Note 11)



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Typical Application (Continued)

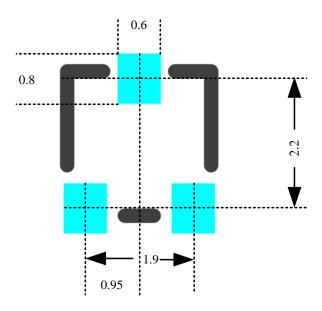


Figure 16. AH9247 Layout Pattern Mechanical Dimensions (Unit: mm)

Note 11:

The AH9247 is an ultra-sensitive Hall-effect switch with digital latched output. It is very sensitive for the magnetic field. As a result, extreme care is required with respect to the pattern layout when designing application circuits. (Figure 15. is a typical application reference, Figure 16. is AH9247 layout pattern mechanical dimensions.)

*1. Ground and VCC Wiring Layout

Insert a capacitor (recommended value: 10nF or larger) as near as possible to the space between the VCC pin and GND pin.

*2. Positioning the External Components

The external components such as C2 (recommended

value: 100pF) that are connected to ground must be connected with lines that are as short as possible. External components connected between IC pins must be placed as near to the pins as possible.

*3. Pad Layout Around Hall Switch

Place some large current lines and some elements that have magnetism, such as speaker and DC Fan, as far to the Hall switch as possible.

*4. GND Pattern

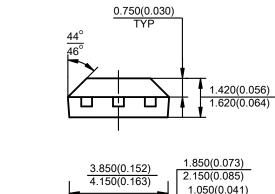
If possible, GND pattern is as large as possible so that the power dissipation from the NB inner case or solder machine can dissipate quickly.

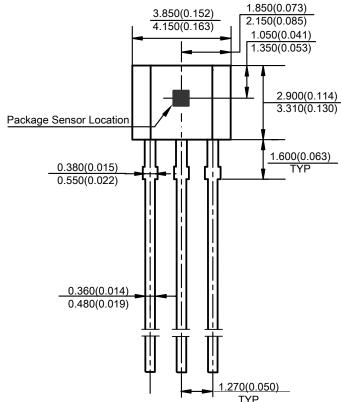


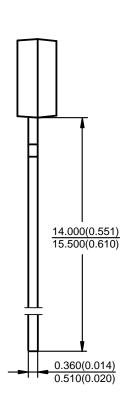
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Mechanical Dimensions

TO-92S-3 Unit: mm(inch)





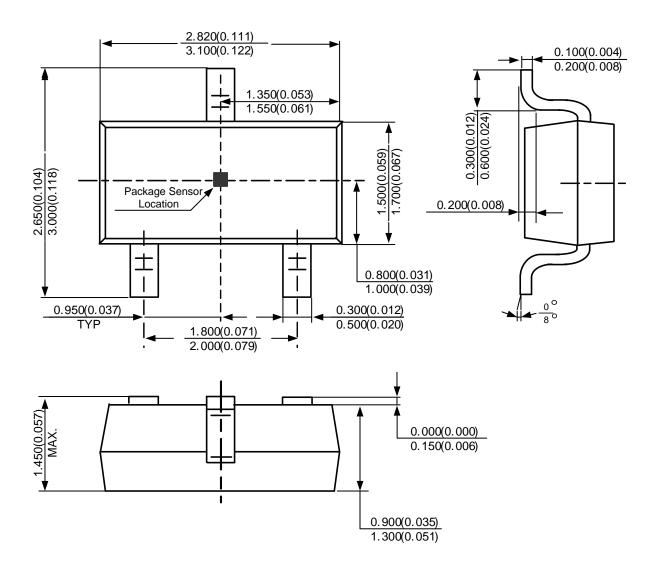




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Mechanical Dimensions (Continued)

SOT-23-3 Unit: mm(inch)

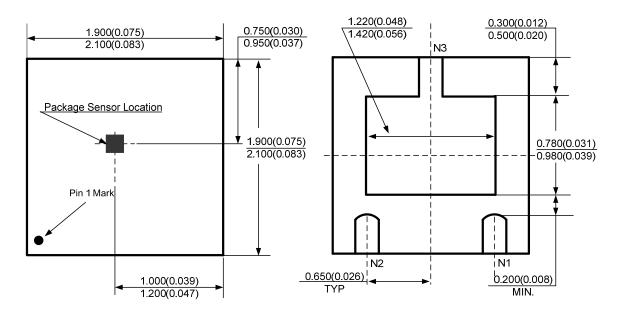


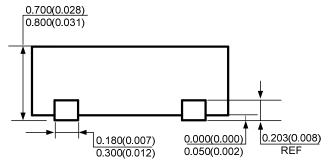


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Mechanical Dimensions (Continued)

DFN-2×2-3 Unit: mm(inch)









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